

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number:

73780-1234

Status:

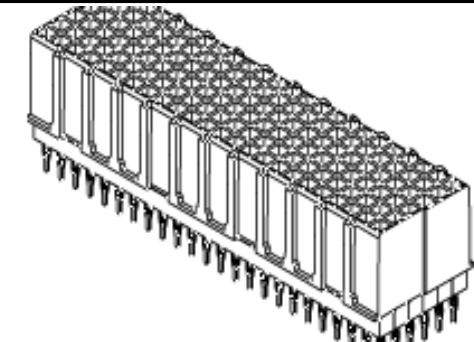
Active

Overview:

HDM®

Description:

2.00mm Pitch HDM® Board-to-Board Daughtercard Receptacle, Vertical, Signal Module, 144 Circuits, Mounted Height 14.00mm, Pin Length 2.00mm, Solder Tail



Series

image - Reference only

Documents:

- [3D Model](#)
- [Drawing \(PDF\)](#)
- [Product Specification PS-73780-999 \(PDF\)](#)
- [Test Summary TS-73670-990 \(PDF\)](#)
- [RoHS Certificate of Compliance \(PDF\)](#)

General

Product Family	Backplane Connectors
Series	73780
Application	Daughtercard, Mezzanine
Comments	Solder Tail
Component Type	PCB Receptacle
Overview	HDM®
Product Name	HDM®
Style	N/A
UPC	822348495566

Physical

Circuits (Loaded)	144
Circuits (maximum)	144
Color - Resin	Black
Durability (mating cycles max)	250
First Mate / Last Break	No
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Copper-Nickel-Tin
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	20.030/g
Number of Columns	24
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length	2.50mm
PCB Locator	No
PCB Retention	None
PCB Thickness - Recommended	1.60mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	2.540µm
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole

Electrical

Current - Maximum per Contact	15A, 1A
-------------------------------	---------

EU RoHS

ELV and RoHS

Compliant

REACH SVHC

Contains SVHC: No

Low-Halogen Status

Low-Halogen

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series
73780Series

Mates With
HDM® Board-to-Board Backplane Header
73642 , 73643 , 73644 , 73942 , 73943 ,
73944 , 74349 , 74428. HDM® Board-to-
Board Stacking Header 73769 , 73770 ,
73782 , 73783 , 73771

Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	5
Lead-free Process Capability	Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	1
Process Temperature max. C	260

Material Info

Reference - Drawing Numbers

Product Specification	PS-73780-999
Sales Drawing	SD-73780-004
Test Summary	TS-73670-990

HDM and High Density Metric are trademarks of Amphenol Corporation

This document was generated on 10/05/2012

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION